

# MMDL6050T1G, SMMDL6050T1G

## Switching Diode

### Features

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

### MAXIMUM RATINGS

| Rating                     | Symbol          | Value | Unit |
|----------------------------|-----------------|-------|------|
| Continuous Reverse Voltage | $V_R$           | 70    | Vdc  |
| Peak Forward Current       | $I_F$           | 200   | mAdc |
| Peak Forward Surge Current | $I_{FM(surge)}$ | 500   | mAdc |

### THERMAL CHARACTERISTICS

| Characteristic                                                                                                | Symbol          | Max         | Unit                       |
|---------------------------------------------------------------------------------------------------------------|-----------------|-------------|----------------------------|
| Total Device Dissipation FR-5 Board<br>(Note 1) @ $T_A = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$ | $P_D$           | 200<br>1.57 | mW<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance, Junction-to-Ambient                                                                       | $R_{\theta JA}$ | 635         | $^\circ\text{C/W}$         |
| Junction and Storage Temperature                                                                              | $T_J, T_{stg}$  | -55 to 150  | $^\circ\text{C}$           |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 Minimum Pad.

### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|----------------|--------|-----|-----|------|
|----------------|--------|-----|-----|------|

#### OFF CHARACTERISTICS

|                                                                                                            |            |              |            |                 |
|------------------------------------------------------------------------------------------------------------|------------|--------------|------------|-----------------|
| Reverse Breakdown Voltage<br>( $I_{(BR)} = 100 \mu\text{Adc}$ )                                            | $V_{(BR)}$ | 70           | –          | Vdc             |
| Reverse Voltage Leakage Current<br>( $V_R = 50 \text{ Vdc}$ )                                              | $I_R$      | –            | 0.1        | $\mu\text{Adc}$ |
| Forward Voltage<br>( $I_F = 1.0 \text{ mAdc}$ )<br>( $I_F = 100 \text{ mAdc}$ )                            | $V_F$      | 0.55<br>0.85 | 0.7<br>1.1 | Vdc             |
| Reverse Recovery Time<br>( $I_F = I_R = 10 \text{ mAdc}$ , $I_{R(REC)} = 1.0 \text{ mAdc}$ )<br>(Figure 1) | $t_{rr}$   | –            | 4.0        | ns              |
| Capacitance<br>( $V_R = 0 \text{ V}$ )                                                                     | $C$        | –            | 2.5        | pF              |

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

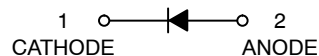


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PLASTIC  
SOD-323  
CASE 477  
STYLE 1



### MARKING DIAGRAM



5A = Device Code  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

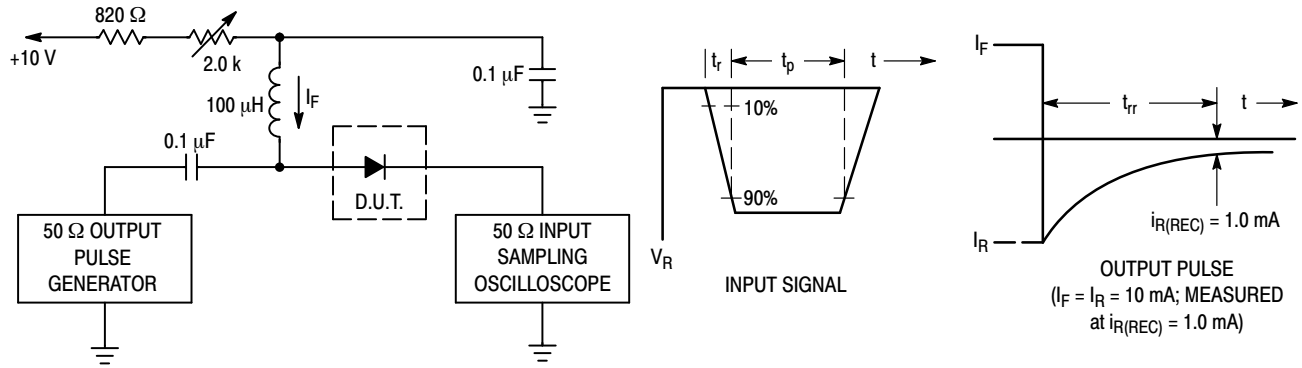
\*Date Code orientation may vary depending upon manufacturing location.

### ORDERING INFORMATION

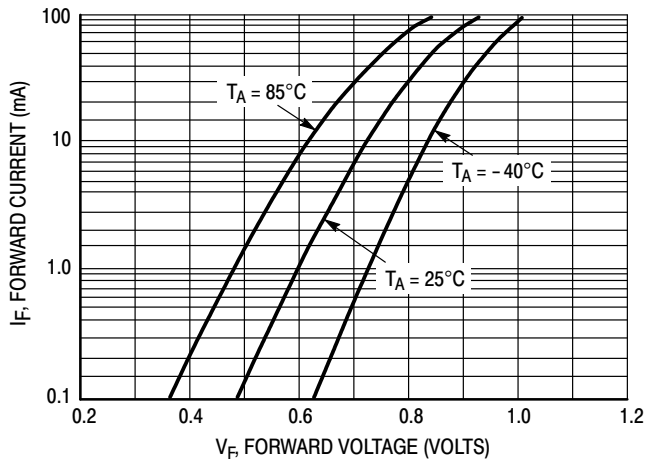
| Device       | Package              | Shipping†              |
|--------------|----------------------|------------------------|
| MMDL6050T1G  | SOD-323<br>(Pb-Free) | 3,000 /<br>Tape & Reel |
| SMMDL6050T1G | SOD-323<br>(Pb-Free) | 3,000 /<br>Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

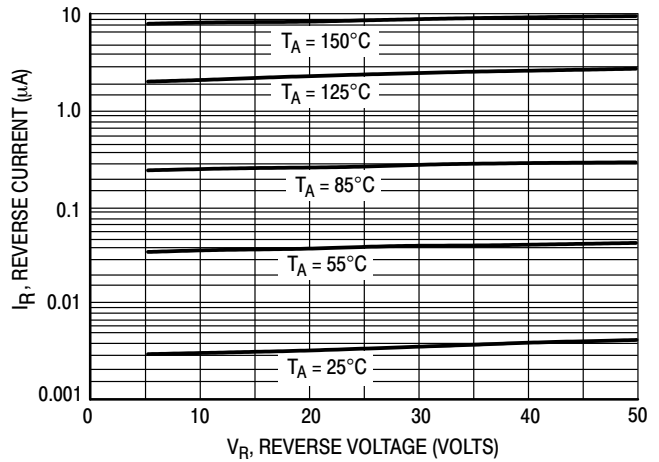
## MMDL6050T1G, SMMDL6050T1G



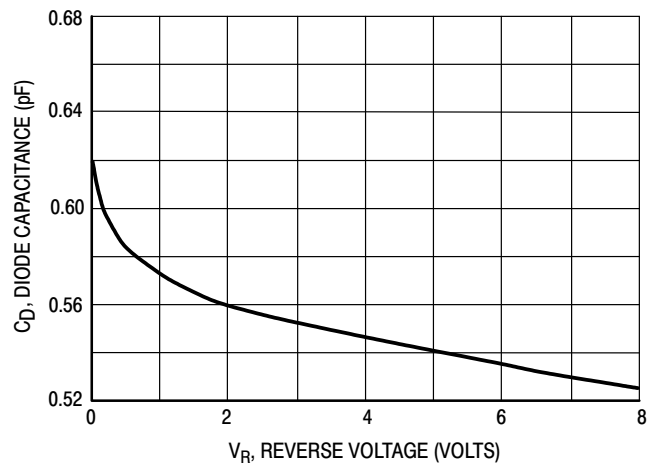
**Figure 1. Recovery Time Equivalent Test Circuit**



**Figure 2. Forward Voltage**



**Figure 3. Leakage Current**



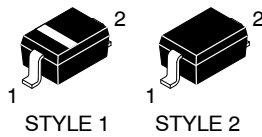
**Figure 4. Capacitance**

# MECHANICAL CASE OUTLINE

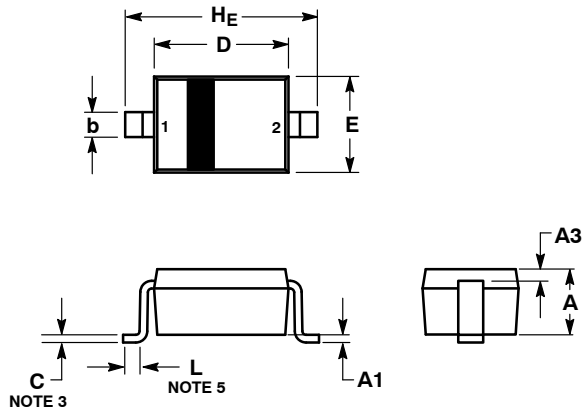
## PACKAGE DIMENSIONS

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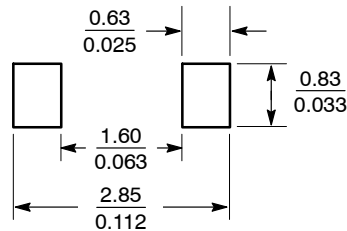
ON



SCALE 4:1



### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SOD-323  
CASE 477-02  
ISSUE H

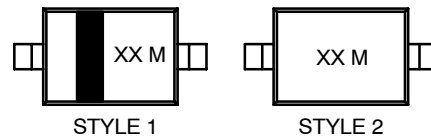
DATE 13 MAR 2007

#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURED FROM END OF RADIUS.

| DIM | MILLIMETERS |      |       | INCHES    |       |       |
|-----|-------------|------|-------|-----------|-------|-------|
|     | MIN         | NOM  | MAX   | MIN       | NOM   | MAX   |
| A   | 0.80        | 0.90 | 1.00  | 0.031     | 0.035 | 0.040 |
| A1  | 0.00        | 0.05 | 0.10  | 0.000     | 0.002 | 0.004 |
| A3  | 0.15 REF    |      |       | 0.006 REF |       |       |
| b   | 0.25        | 0.32 | 0.4   | 0.010     | 0.012 | 0.016 |
| C   | 0.089       | 0.12 | 0.177 | 0.003     | 0.005 | 0.007 |
| D   | 1.60        | 1.70 | 1.80  | 0.062     | 0.066 | 0.070 |
| E   | 1.15        | 1.25 | 1.35  | 0.045     | 0.049 | 0.053 |
| L   | 0.08        |      |       | 0.003     |       |       |
| HE  | 2.30        | 2.50 | 2.70  | 0.090     | 0.098 | 0.105 |

### GENERIC MARKING DIAGRAM\*



XX = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLE 1:  
PIN 1. CATHODE (POLARITY BAND)  
2. ANODE

STYLE 2:  
NO POLARITY

|                  |             |                                                                                                                                                                                  |
|------------------|-------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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| DESCRIPTION:     | SOD-323     | PAGE 1 OF 1                                                                                                                                                                      |

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